



## 特点

- \* 外形尺寸: 116.8 × 61.0 × 12.7 mm
- \* 工业 标准全砖封装和引脚
- \* 高效率、高功率密度
- \* 基板工作温度 100℃

## Features

- \* Size: 4.60 × 2.40 × 0.50 inch
- \* Industry Standard Full-Brick Package and Footprint
- \* High Efficiency, High Power Density
- \* 100℃ Baseplate Operation

### 输入特性(Input)

		注释(Notes and Conditions)	
输入电压范围(Input Voltage Range)	36~76Vdc	80Vdc Max	
遥控功能(Remote On/Off Function)			
负逻辑(Negative Logic)	开启(On)	1mA ≤ I <sub>ON/OFF</sub> ≤ 5mA	+ON/OFF与-ON/OFF之间
	关闭(Off)	悬空(Open Circuit)	+ON/OFF与-ON/OFF之间

### 输出特性(Output)

		注释(Notes and Conditions)	
输出电压精度(Voltage Set-Point Accuracy)	± 1%	V <sub>nom</sub> and I <sub>nom</sub>	
输出电压调节范围(Output Voltage Trim Range)	- 40%~ + 10%		
源效应(Line Regulation)	± 0.2%V <sub>o</sub>	V <sub>imin</sub> ~V <sub>imax</sub> , I <sub>nom</sub>	
负载效应(Load Regulation)	± 0.5%V <sub>o</sub>	10%~100%I <sub>nom</sub> , V <sub>nom</sub>	
输出过压保护(Output Overvoltage Protection)	115%~135%V <sub>o</sub>		
输出过流保护点(Current Limit Threshold Range)	105%~140%I <sub>o</sub>		
短路保护(Short-Circuit Protection)	连续可恢复 (Continuous, Automatic Recovery)		
I <sub>OG</sub> 信号(I <sub>OG</sub> Signal)	模块正常工作信号, 此端呈低电平状态, 集电极开路输出 (Converter Operation Good Signal, Condition of Low Level, Open Collector Output)		
PC信号(PC Signal)	并联运行时, 互联 PC 端可实现均流 (By Connecting the PC Terminal, Output Current Balance Operation)		
AUX端子(AUX Terminal)	辅助电源输出端子, 7~10Vdc (Auxiliary Power Supply for External Signal, 7~10Vdc)		
瞬态响应(Dynamic Response)			
过冲幅度(Peak Deviation)	± 5%V <sub>o</sub>	25%-50%-25% of I <sub>nom</sub>	
恢复时间(Settling Time)	200 μs	and 50%-75%-50% of I <sub>nom</sub>	

### 一般特性(General)

		注释(Notes and Conditions)	
温度系数(Temperature Coefficient)	± 0.02%/℃		
隔离电压(Isolation Voltage)			
输入与输出(Input-Output)	1500Vdc 1min		
输入与外壳(Input-Case)	1500Vdc 1min		
输出与外壳(Output-Case)	500Vdc 1min		
工作基板温度(Operating Baseplate Temperature)	- 40℃ ~ + 100℃		
贮存温度(Storage Temperature)	- 40℃ ~ + 100℃		
冷却方式(Cooling)	加装散热器或强制风冷	Attach Heatsink or Forced Convection	
过温保护(Thermal Shutdown Range)	+ 100℃ ~ + 110℃	基板温度(Baseplate Temperature)	
平均故障间隔时间(MTBF)	2 × 10 <sup>5</sup> h	MIL-HDBK-217	

注: 除非另有说明, 指标一般在标称输入电压、满载和 25℃ 基板温度下测得。

Note: All specifications are typical at nominal input, full load at 25℃ baseplate temperature unless otherwise stated.

